

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHIN-YI YANG	06/29/2020
HSIN-YEN HUANG	06/29/2020
MING-HAN LEE	06/29/2020
SHAU-LIN SHUE	06/29/2020
YU-CHEN CHAN	06/29/2020
MENG-PEI LU	06/29/2020
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16908942
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ATTORNEY DOCKET NUMBER:	TSMCP1217US
NAME OF SUBMITTER:	DAVID W. POTASHNIK
SIGNATURE:	/David W. Potashnik/
DATE SIGNED:	07/27/2020

PATENT

Total Attachments: 8

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PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):

Shin-Yi Yang

Assignor(s):

Hsin-Yen Huang

Assignor(s):

Ming-Han Lee

Assignor(s):

Shau-Lin Shue

Assignor(s):

Yu-Chen Chan

Assignor(s):

Meng-Pei Lu

Assignee:

Taiwan Semiconductor Manufacturing Co., Ltd.
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled
"PROTECTION LINER ON INTERCONNECT WIRE TO ENLARGE PROCESSING
WINDOW FOR OVERLYING INTERCONNECT VIA" for which:

a non-provisional application for United States Letters Patent:

- ☒ was executed on even date preparatory to filing (each inventor should sign this
Assignment on the same day as he/she signs the Declaration); or
- ☐ was filed on _____ and accorded U.S. Serial No. _____; or

☐ I hereby authorize and request my attorney associated with Customer No. 107476, to insert on the designated lines below the filing date and application number of said application when known:

U.S. Serial No. _____

filed on _____

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for

TSMC Docket No. P20200625US00
Docket No. TSMCP1217US

United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

2020.6.29
Date

Shin-Yi Yang
Name 1st Inventor Shin-Yi Yang

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2020.6.29
Date

Name Hsin-Yen Huang 2nd Inventor Hsin-Yen Huang

TSMC Docket No. P20200625US00
Docket No. TSMCP1217US

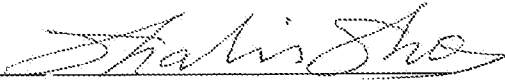
2020/06/29
Date


Name 3rd Inventor Ming-Han Lee

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2020.6.29

Date


Name 4th Inventor Shau-Lin Shue

TSMC Docket No. P20200625US00
Docket No. TSMCP1217US

2006.6.29
Date

Yu-Chen Chan
Name 5th Inventor Yu-Chen Chan

TSMC Docket No. P20200625US00
Docket No. TSMCP1217US

2020.06.29
Date

Meng-Pei Lu
Name 6th Inventor Meng-Pei Lu